

REMARKS

Claims 1-7 are pending for further examination.

Claims 8-18 were withdrawn from consideration as the result of a restriction requirement.

In the Office action, the claims were rejected as follows:

- (1) Claims 1-4 and 6 were rejected as anticipated by U.S. Patent Publication 2003/0164554 (Fee et al.).
- (2) Claim 5 was rejected as unpatentable over the Fee et al. publication in view of U.S. Patent Publication 2002/0056926 (Jung et al.).
- (3) Claim 7 was rejected as unpatentable over the Fee et al. publication in view of U.S. Patent No. 6,836,009 (Koon et al.).

Claim 1 recites a circuit device comprising a conductive pattern; a circuit element, affixed onto the conductive pattern; and an insulating resin that seals the conductive pattern and the circuit element while exposing at least a bottom surface of the conductive pattern.

Claim 1 has been amended to clarify that recessed areas are in side surfaces of the insulating resin such that outwardly facing outer peripheral parts of the conductive pattern are exposed from within the recessed areas. An example is illustrated in FIG. 1 in which a resin is identified by reference numeral 14 and includes recesses 15. Outwardly facing peripheral parts of the bonding pads 12 are exposed from within the recesses 15.

In view of the amendments and the following remarks, applicant respectfully requests reconsideration and withdrawal of the rejections.

The Fee et al. patent discloses a semiconductor package 10 that includes a die paddle 14 and conductive elements 16. A semiconductor die 12 is mounted on the die paddle 14. An encapsulant 26 covers the die 12 and conductive elements 16.

The bottom of the package is illustrated in FIG. 1 of the Fee et al. patent. Inner and outer rows of 18A, 18B of conductive elements 16 are separated from one another by recesses 30. The recesses 30 extend to the sides of the package and also are shown in FIG. 2.

Even if the outwardly facing peripheral parts of the conductive elements 18B were considered to be exposed, those portions of the conductive elements are not exposed "from within" the recessed areas 30, as recited in pending claim 1.

Similarly, even if the outwardly facing parts of the conductive elements 18A were considered to be exposed "from within" the recessed areas 30, those parts are not "outer peripheral" parts, as recited in pending claim 1.

Therefore, the particular arrangement of the recesses and conductive pattern recited in claim 1 is very different from the arrangement disclosed by the Fee et al. patent. There is simply no disclosure or suggestion of "recessed areas are in side surfaces of the insulating resin such that outwardly facing outer peripheral parts of the conductive pattern are exposed from within the recessed areas," as recited in pending claim 1.

Neither the Jung et al. or the Koon et al. patents disclose or suggest the features missing from the Fee et al. patent.

At least for the foregoing reasons, claim 1, as well as dependent claims 2-6, should be allowed.

It is believed that all of the pending claims have been addressed. However, the absence of a reply to a specific rejection, issue or comment does not signify agreement with or concession of that rejection, issue or comment. In addition, because the arguments made above may not be exhaustive, there may be reasons for patentability of any or all pending claims (or other claims) that have not been expressed. Finally, nothing in this paper should be construed as an intent to concede any issue with regard to any claim, except as specifically stated in this paper, and the amendment of any claim does not necessarily signify concession of unpatentability of the claim prior to its amendment.

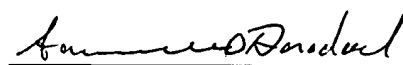
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Respectfully submitted,

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